

THERMOCOMP™ LDS COMPOUNDS FOR 3D-MID

SOLUTION STORY: ELECTRONICS

HIGHLIGHTS

- Integration for structural and functional parts
- Complex and fine line design
- Thin-wall design
- Wider color range
- System cost effective

SHORT STORY

THERMOCOMP LDS (Laser Direct Structuring) compounds can help drive productivity and design cycle flexibility, through part consolidation and miniaturization vs. conventional technologies, such as metal stamping. This can potentially provide system cost-out due to a shorter value chain and faster market introduction. An miD is a thermoplastic part with an integrated electronic circuit.

- 3D means three-dimensional solutions are possible
- A 3D circuit is realized by structuring the metal layers
- A three-dimensional PCB is created

Laser Direct Structuring allows customers to make 3D parts and activate the 3D surface for proper metallization, and it enables 3D printed circuit boards and antennas.

CONTACT US

Reach out to learn more about electronic solutions from SABIC.
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